PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3425181

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ming-Tse Lin	01/18/2013
Chu-Fu Lin	01/18/2013
Chien-Li Kuo	01/18/2013
Yung-Chang Lin	01/18/2013

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14791265

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP1561USA1
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	07/03/2015

Total Attachments: 8

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PATENT REEL: 035976 FRAME: 0031

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PATENT REEL: 035976 FRAME: 0032

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I here	by declare that:			
This declaration is directed to:				
The attached application, or	•			
☐ United States application nu	ımber	file	d on	, or
☐ PCT international applicatio	n number		filed on	
The above-identified application was	made or authorized	o be made by m	ie.	
I believe that I am the original invent application.	or or an original joint	nventor of a clai	med invention i	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				le
In consideration of the payment by	UNITED MICROE	LECTRONICS	having a p	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-C	hu City 300,	Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an			he receipt of wh	nich is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all impr tion and, in and to, al r any continuations, c	ovements which Letters Patent t ontinuation-in-pa	are disclosed in o be obtained for tr, divisions, re	n the or said newals,
I hereby covenant that no assignmer entered into which would conflict with		encumbrance h	as been or will	be made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters estify as to the same i	Patent and legal any interferenc	equivalents as e, litigation prod	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	olication, said invention ecessary or desirable	n and said Lette to carry out the p	rs Patent and soroposes thereo	aid of. (Date of signing)
Note: An application data sheet (PTC				_

Page 1 of 8

Inventor: Ming-Tse Lin Date: JAN 18 2013

Signature: Ming - Tse Lin

Page 2 of 8

NPO#NAU-PI561-USA:0 CUST#UMCD-2012-0321 F#NPO-P0002E-US1201 DSC0-101U014773

PATENT

REEL: 035976 FRAME: 0034

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or	•			
☐ United States application nu	ımber	_filed o	n	_ , or
☐ PCT international applicatio	n number	filed on		
The above-identified application was	s made or authorized to be made l	by me.		
I believe that I am the original invent application.	or or an original joint inventor of a	claimed	I invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	UNITED MICROELECTRON CORP.	lics	having a postal a	ddress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu	City 300, Taiwa	an, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar		00), the r	eceipt of which is I	nereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat r any continuations, continuation-i	hich are ent to be n-part, d	disclosed in the obtained for said ivisions, renewals	,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has b	een or will be mad	de or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and lestify as to the same in any interfe	legal equ rence, lit	ivalents as may b igation proceeding	е
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said Lacessary or desirable to carry out	etters Pathe	atent and said oses thereof.	e of signing)
Note: An application data sheet (PT0 inventive entity, must accompany thi				

Page 3 of 8

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Chu-Fu Lin		Date:	MAL	1 8 2013	
Signature:	Chu-Fu	Sim				

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NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321 F#NPO-P0002E-US1201 DSC0-101U014773

PATENT

REEL: 035976 FRAME: 0036

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I hereb This declaration is directed to:	y declare that:			
☑ The attached application, or				
☐ United States application number file			on	, or
☐ PCT international application	number	file	d on	
The above-identified application was	made or authorized to l	oe made by me.		
I believe that I am the original invento application.	or or an original joint inv	entor of a claime	d invention in	the
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impris				•
	UNITED MICROELE CORP.	ECTRONICS	having a pos	stal address of
No.3, Li-Hsin Road 2, Science-	Based Industrial P	ark, Hsin-Chu	City 300, T	aiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	I of the sum of One Do d valuable consideration	llar (\$ 1.00), the 1.	receipt of whic	ch is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, and	d to any and all improve ion and, in and to, all Le any continuations, cont	ements which are etters Patent to b inuation-in-part,	e disclosed in e obtained for divisions, rene	the · said ewals,
I hereby covenant that no assignmen entered into which would conflict with		ncumbrance has	been or will be	e made or
I further covenant that ASSIGNEE wil and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	ion and said Letters Pa stify as to the same in a	tent and legal ed ny interference, l	uivalents as n itigation proce	nay be
representatives any and all papers, in maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	ication, said invention a cessary or desirable to	and said Letters F carry out the prop	Patent and sai	
Note: An application data sheet (PTO inventive entity, must accompany this				

Page 5 of 8

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

Inventor: Chien-Li Kuo

Date: JAN 18 2013

Signature:

Page 6 of 8

F#NPO-P0002E-US1201 DSC0-101U014773

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

> PATENT REEL: 035976 FRAME: 0038

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed o	on	, or
☐ PCT international application	n number	file	d on	
The above-identified application was	made or authorized	to be made by me.		
I believe that I am the original invente application.	or or an original joint	inventor of a claime	d invention in	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri				le
In consideration of the payment by	UNITED MICROE CORP.	LECTRONICS	having a po	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Chu	City 300,	Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One d valuable considera	Dollar (\$ 1.00), the tion.	receipt of wh	ich is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified application or substitutes, or extensions thereof, ar	nd to any and all impr tion and, in and to, al any continuations, c	ovements which are Letters Patent to bontinuation-in-part,	e disclosed ir e obtained fo divisions, rer	n the or said newals,
I hereby covenant that no assignmer entered into which would conflict with		encumbrance has	been or will t	oe made or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters stify as to the same in	Patent and legal ed any interference, l	uivalents as itigation proc	may be
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said inventio cessary or desirable	n and said Letters f to carry out the pro	Patent and sa poses thereo	aid f. _(Date of signing)
Note: An application data sheet (PTC				

Page 7 of 8

LEGAL NAME OF INVENTOR(ASSIGNOR)

inventor:

Yung-Chang Lin

Date:

JAN 18 2013

Signature:

Yung-cher gi

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Page

F#NPO-P0002E-US1201 DSC0-101U014773

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

> PATENT REEL: 035976 FRAME: 0040

RECORDED: 07/03/2015